



COPY OF PAPERS  
ORIGINALLY FILED

ney Docket No. 23537.90

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application:

Serial No.: 09/806,252  
Filed: March 27, 2001

RECEIVED

AUG 06 2002

Technology Center 2600

July 24, 2002

Hon. Commissioner of Patents and Trademarks  
Washington D.C. 20231

**CHANGE OF ADDRESS**

S I R:

Please address all future correspondence concerning the above application  
or any patent to issue to the following:

William H. Dippert  
Reed Smith LLP  
599 Lexington Avenue  
29<sup>th</sup> Floor  
New York, New York 10022  
(212) 521-5400

Customer No. 026418

Respectfully submitted,

*William H. Dippert*  
William H. Dippert  
Reg. No. 26,723